

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	1.1Ω@10V	300mA
	1.4Ω@4.5V	

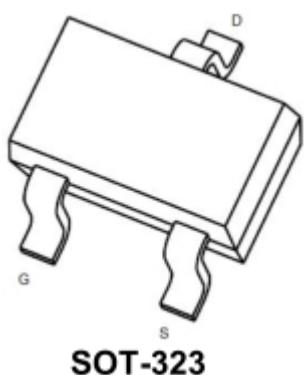
Feature

- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding
- ESD protected

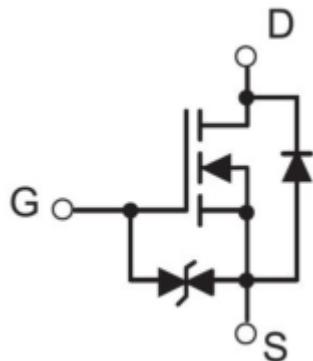
Application

- Power Management in Note book
- Portable Equipment
- Battery Powered System

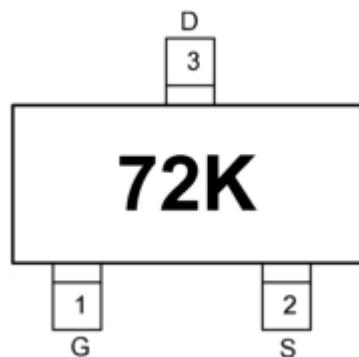
Package



Circuit diagram



Marking



Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	300	mA
Plused Drain Current ¹	I_{DM}	800	mA
Power Dissipation	P_D	0.2	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	625	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$



ZL MOSFET

2N7002KW

Electrical characteristics

(T_A=25°C, unless otherwise noted)

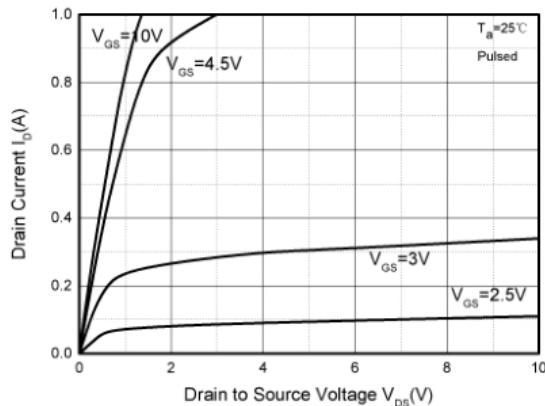
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60			V
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	1.5	2.5	V
Gate-body leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±10	uA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V			1	uA
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 500mA V _{GS} = 4.5V, I _D = 200mA		1.1	1.6	Ω
Dynamic characteristics						
Total Gate Charge	Q _g	V _{DS} =10V, V _{GS} =4.5V, I _D =250mA		0.3		nC
Gate-Source Charge	Q _{gs}			0.2		
Gate-Drain Charge	Q _{gd}			0.08		
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHz		30	50	pF
Output Capacitance	C _{oss}			4.2	25	
Reverse Transfer Capacitance	C _{rss}			2.9	5	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V, I _D =200mA, V _{GEN} =10V, R _G = 25Ω		3.9		ns
Turn-On Rise Time	t _R			3.4		
Turn-Off Delay Time	t _{d(off)}			15.7		
Turn-Off Fall Time	t _F			9.9		
Source-Drain Diode Characteristics						
Diode Forward voltage	V _{SD}	V _{GS} = 0V, I _S =200mA		0.82	1.3	V



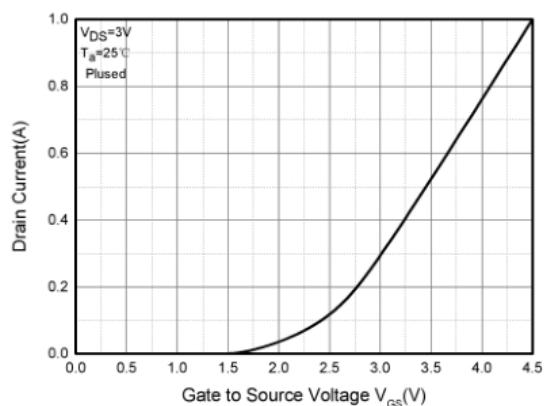
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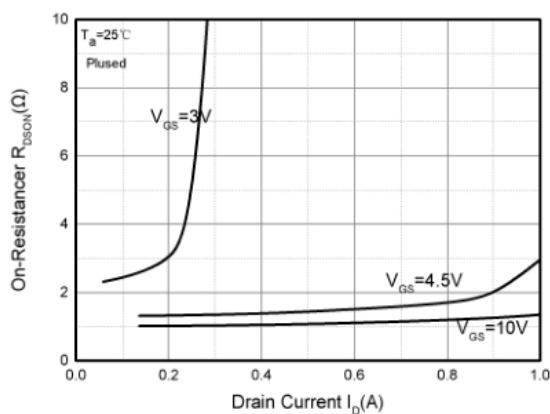
Typical Characteristics



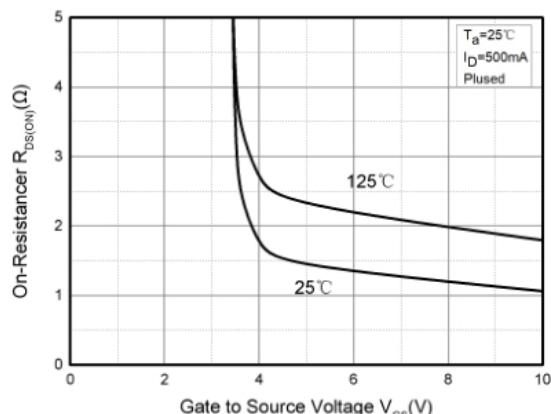
Output Characteristics



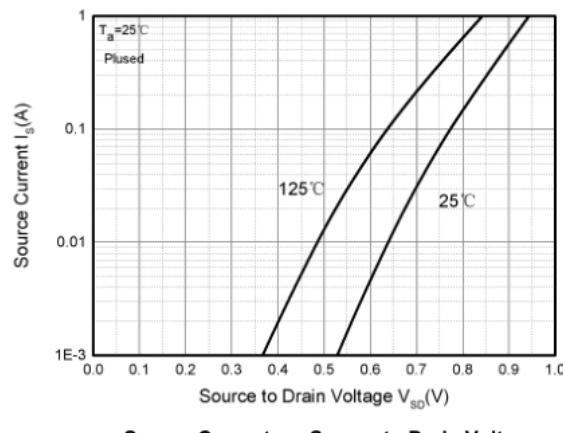
Transfer Characteristics



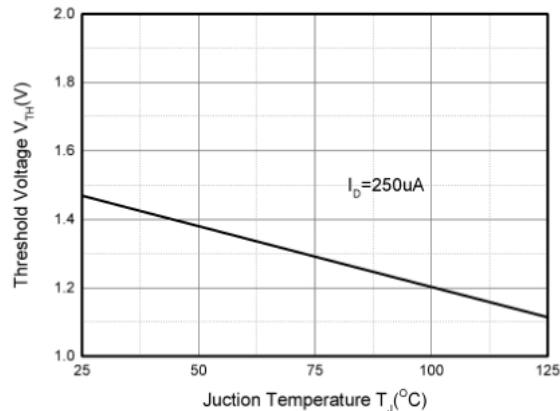
On-Resistance vs. Drain current



On-Resistance vs. Gate to Source Voltage

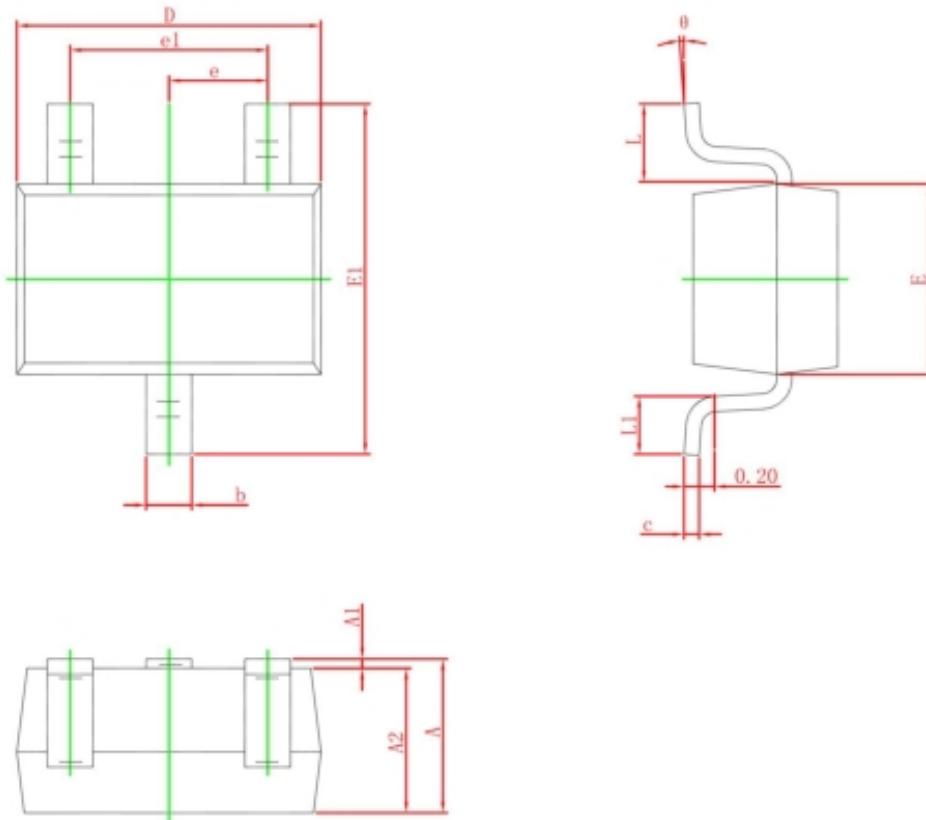


Source Current vs. Source to Drain Voltage



Threshold voltage vs. Junction temperature

SOT-323 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.000	2.450	0.085	0.096
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.525 REF.		0.021 REF.	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°